

Title (en)

Cmos/mems integrated ink jet print head and method of forming same

Title (de)

Cmos/mems integrierter Tintenstrahldruckkopf und Verfahren zu seiner Herstellung

Title (fr)

Tête à jet d'encre intégrée Cmos/mems et méthode de fabrication

Publication

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Application

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Priority

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Abstract (en)

An ink jet print head is formed of a silicon substrate that includes an integrated circuit formed therein for controlling operation of the print head. The silicon substrate has one or more ink channels formed therein along the longitudinal direction of the nozzle array. An insulating layer or layers overlie the silicon substrate and has a series or an array of nozzle openings or bores formed therein along the length of the substrate and each nozzle opening communicates with an ink channel. The area comprising the nozzle openings forms a generally planar surface to facilitate maintenance of the printhead. A heater element is associated with each nozzle opening or bore for asymmetrically heating ink as ink passes through the nozzle opening or bore. <IMAGE>

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CPC (source: EP)

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Citation (applicant)

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